Thermal Data

D2PAK

PACKAGE MATERIAL LIST

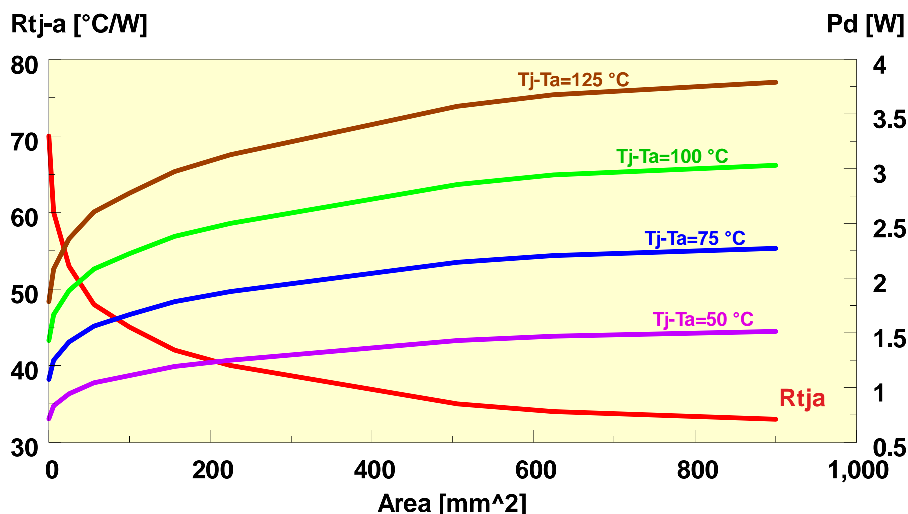
item #	material	thickness
leadframe	copper	0.5 mm
slug	high thermal conductivity Cu	0.5 mm
die attach	soft solder (glu)	15-50 µm
molding compound	epoxy resin	2.23-2.35 mm

Charts enclosed :

1) Thermal Resistance and Maximum Power Dissipated

2) Zth(j-a) vs time width and die size

1)



Tj = Ta + (Pd*Rtj-a)
2 oz. Copper

2)